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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I²C, SPI, UART/USART, USB
Peripherals	DMA, I²S, POR, PWM, WDT
Number of I/O	48
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	176K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamg55j19b-au

SAM G55G / SAM G55J

Atmel | SMART ARM-based Flash MCU

SUMMARY DATASHEET

Description

The Atmel® | SMART SAM G55 is a series of Flash microcontrollers based on the high-performance 32-bit ARM® Cortex®-M4 RISC processor with FPU (Floating Point Unit). It operates at a maximum speed of 120 MHz and features 512 Kbytes of Flash and up to 176 Kbytes of SRAM. The peripheral set includes eight flexible communication units comprising USARTs, SPIs and I^2C-bus interfaces (TWIs), two three-channel general-purpose 16-bit timers, two I^2S controllers, one-channel pulse density modulation, one 8-channel 12-bit ADC, one real-time timer (RTT) and one real-time clock (RTC), both located in the ultra low-power backup area.

The Atmel | SMART SAM G55 devices have three software-selectable low-power modes: Sleep, Wait and Backup. In Sleep mode, the processor is stopped while all other functions can be kept running. In Wait mode, all clocks and functions are stopped but some peripherals can be configured to wake up the system based on events, including partial asynchronous wakeup (SleepWalking™). In Backup mode, RTT, RTC and wakeup logic are running.

For power consumption optimization, the flexible clock system offers the capability of having different clock frequencies for some peripherals. Moreover, the processor and bus clock frequency can be modified without affecting the peripheral processing.

The real-time event management allows peripherals to receive, react to and send events in Active and Sleep modes without processor intervention.

The SAM G55 devices are general-purpose low-power microcontrollers that offer high performance, processing power and small package options combined with a rich and flexible peripheral set. With this unique combination of features, the SAM G55 series is suitable for a wide range of applications including consumer, industrial control and PC peripherals.

The device operates from 1.62V to 3.6V and is available in three packages: 49-pin WLCSP, 64-pin QFN and 64-pin LQFP.

Features

- Core
  - ARM Cortex-M4 with up to 16 Kbytes SRAM on I/D bus providing 0 wait state execution at up to 120 MHz (1)
  - Memory Protection Unit (MPU)
  - DSP Instructions
  - Floating Point Unit (FPU)
  - Thumb®-2 instruction set

Note: 1. 120 MHz with $V_{DDCOREXT120}$ or with V_{DDCORE} trimmed by regulator.

- Memories
  - Up to 512 Kbytes embedded Flash
  - Up to 176 Kbytes embedded SRAM
  - 8 Kbytes ROM with embedded boot loader, single-cycle access at full speed
- System
  - Embedded voltage regulator for single-supply operation
  - Power-on reset (POR) and Watchdog for safe operation
  - Quartz or ceramic resonator oscillators: 3 to 20 MHz with clock failure detection and 32.768 kHz for RTT or system clock
  - High-precision 8/16/24 MHz factory-trimmed internal RC oscillator. In-application trimming access for frequency adjustment
  - Slow clock internal RC oscillator as permanent low-power mode device clock
  - PLL range from 48 MHz to 120 MHz for device clock
  - PLL range from 24 MHz to 48 MHz for USB device and USB OHCI
  - Up to 30 peripheral DMA (PDC) channels
  - 256-bit General-Purpose Backup Registers (GPBR)
  - 16 external interrupt lines
- Peripherals
  - 8 flexible communication units supporting:
    - USART
    - SPI
    - Two-wire Interface (TWI) featuring TWI masters and high-speed TWI slaves
  - Crystal-less USB 2.0 Device and USB Host OHCI with On-chip Transceiver
  - 2 Inter-IC Sound Controllers (I^2S)
  - 1 Pulse Density Modulation Interface (PDMIC) (supports up to two microphones)
  - 2 three-channel 16-bit Timer/Counters (TC) with capture, waveform, compare and PWM modes
  - 1 48-bit Real-Time Timer (RTT) with 16-bit prescaler and 32-bit counter
  - 1 RTC with calendar and alarm features
  - 1 32-bit Cyclic Redundancy Check Calculation Unit (CRCCU)
- I/O
  - Up to 48 I/O lines with external interrupt capability (edge or level), debouncing, glitch filtering and on-die series resistor termination. Individually programmable open-drain, pull-up and pull-down resistor and synchronous output
  - Two PIO Controllers provide control of up to 48 I/O lines

- Analog
  - One 8-channel ADC, resolution up to 12 bits, sampling rate up to 500 ksps
- Package
  - 49-lead WLCSP
  - 64-lead LQFP
  - 64-lead QFN
- Operating Temperature Range
  - Industrial (-40°C to +85°C)

1. Configuration Summary

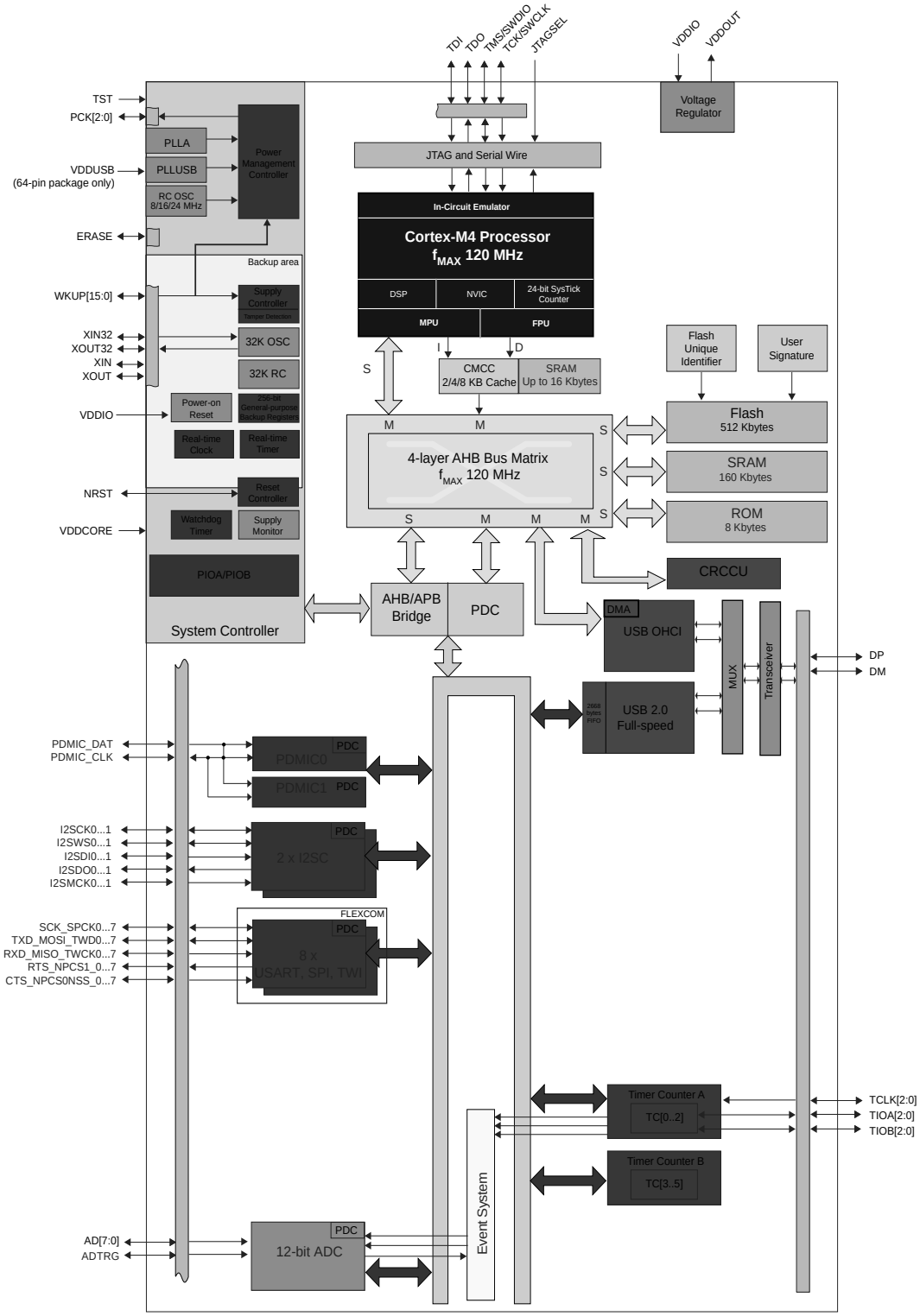
Table 1-1 summarizes the SAM G55 device configurations.

Table 1-1. Configuration Summary

Feature	SAM G55G19	SAM G55J19
Flash	512 Kbytes	512 Kbytes
Cache (CMCC)	up to 8 Kbytes	up to 8 Kbytes
SRAM	160 Kbytes + up to 16 Kbytes (Cache + I/D RAM)	160 Kbytes + up to 16 Kbytes (Cache + I/D RAM)
Package	WLCSP49	QFN64, LQFP64
Number of PIOs	38	48
Event System	Yes	Yes
External Interrupt	16	16
12-bit ADC	8 channels Performance: 500 kSps	8 channels Performance: 500 kSps
16-bit Timer	6 channels (3 external channels)	6 channels (3 external channels)
I2SC/PDM	2 / 1-channel 2-way	2 / 1-channel 2-way
PDC Channels	28	30
USART	7	8
SPI		
TWI		
USB	Full Speed / OHCI	Full Speed / OHCI
CRCCU	1	1
RTT	1 (backup area)	1 (backup area)
RTC	1 (backup area)	1 (backup area)

2. Block Diagram

Figure 2-1. SAM G55 Block Diagram



3. Signal Description

Table 3-1 gives details on the signal names classified by peripheral.

Table 3-1. Signal Description List

Signal Name	Function	Type	Active Level	Voltage Reference	Comments
Power Supplies					
VDDIO	Peripheral I/O Lines, Voltage Regulator, ADC Power Supply	Power	–	–	1.62V to 3.6V
VDDOUT	Voltage Regulator Output	Power	–	–	1.08V to 1.32V
VDDCORE	Core Chip Power Supply	Power	–	–	Connected externally to VDDOUT or $V_{DDCOREXT100}$ or $V_{DDCOREXT120}$
VDDUSB	USB Power Supply	Power	–	–	Only available on 64-pin package
GND	Ground	Ground	–	–	–
Clocks, Oscillators and PLLs					
XIN	Main Oscillator Input	Input	–	VDDIO	Reset state: - PIO input - Internal pull-up disabled - Schmitt Trigger enabled
XOUT	Main Oscillator Output	Output	–	–	
XIN32	Slow Clock Oscillator Input	Input	–	VDDIO	
XOUT32	Slow Clock Oscillator Output	Output	–	–	
PCK0–PCK2	Programmable Clock Output	Output	–	–	Reset state: - PIO input - Internal pull-up enabled - Schmitt Trigger enabled
ICE and JTAG					
TCK	Test Clock	Input	–	VDDIO	No pull-up resistor
TDI	Test Data In	Input	–	VDDIO	No pull-up resistor
TDO	Test Data Out	Output	–	VDDIO	–
TRACESWO	Trace Asynchronous Data Out	Output	–	VDDIO	–
SWDIO	Serial Wire Input/Output	I/O	–	VDDIO	–
SWCLK	Serial Wire Clock	Input	–	VDDIO	–
TMS	Test Mode Select	Input	–	VDDIO	No pull-up resistor
JTAGSEL	JTAG Selection	Input	High	VDDIO	Pull-down resistor
Flash Memory					
ERASE	Flash and NVM Configuration Bits Erase Command	Input	High	VDDIO	Pull-down (15 kΩ) resistor
Reset/Test					
NRST	Microcontroller Reset	I/O	Low	VDDIO	Pull-up resistor
TST	Test Mode Select	Input	–	VDDIO	Pull-down resistor

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Voltage Reference	Comments
PIO Controller - PIOA - PIOB					
PA0–PA31	Parallel I/O Controller A	I/O	–	VDDIO	Pulled-up input at reset. No pull-down for PA3/PA4/PA14
PB0–PB15[1]	Parallel I/O Controller B	I/O	–	VDDIO	Pulled-up input at reset
Wakeup Pins					
WKUP0–15	Wakeup Pin / External Interrupt	I/O	–	VDDIO	Wakeup pins are used also as External Interrupt
Serial Peripheral Interface - SPIx					
MISOx	Master In Slave Out	I/O	–	–	–
MOSIx	Master Out Slave In	I/O	–	–	–
SPCKx	SPI Serial Clock	I/O	–	–	High Speed Pad
NPCS0x	SPI Peripheral Chip Select 0	I/O	Low	–	–
NPCS1x	SPI Peripheral Chip Select	Output	Low	–	–
Two-Wire Interface - TWIx					
TWDx	TWIx Two-wire Serial Data	I/O	–	–	High Speed Pad for TWD0
TWCKx	TWIx Two-wire Serial Clock	I/O	–	–	High Speed Pad for TWDCK0
Universal Synchronous Asynchronous Receiver Transmitter USARTx					
SCKx	USART Serial Clock	I/O	–	–	–
TXDx	USART Transmit Data	I/O	–	–	–
RXDx	USART Receive Data	Input	–	–	–
RTSx	USART Request To Send	Output	–	–	–
CTSx	USART Clear To Send	Input	–	–	–
Timer/Counter - TCx					
TCLKx	TC Channel x External Clock Input	Input	–	–	–
TIOAx	TC Channel x I/O Line A	I/O	–	–	–
TIOBx	TC Channel x I/O Line B	I/O	–	–	–
12-bit Analog-to-Digital Converter - ADC					
AD0–AD7	Analog Inputs	Analog	–	–	–
ADTRG	ADC Trigger	Input	–	–	–
ADVREF	ADC Voltage Reference	Input	–	–	Only available on 64-pin package
Inter-IC Sound Controller - I2SCx					
I2SMCKx	Master Clock	Output	–	–	–
I2SCKx	Serial Clock	I/O	–	–	–
I2SWSx	I^2S Word Select	I/O	–	–	–
I2SDIx	Serial Data Input	Input	–	–	–
I2SDOx	Serial Data Output	Output	–	–	–

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Voltage Reference	Comments
Pulse Density Modulation Interface Controller - PDMICx					
PDMIC_CLK	Pulse Density Modulation Clock	Output	–	–	–
PDMIC_DAT	Pulse Density Modulation Data	Input	–	–	–
USB OHCI/FS - USB					
DM	USB Data -	Analog, Digital	–	WLCSP49: VDDIO 64-pin package: VDDUSB	DM and DP in PIO configuration
DP	USB Data +				

Note: 1. Pull-up disabled on PB8/PB9.

4. Package and Pinout

Table 4-1. SAM G55 Packages

Device	Package
SAM G55G19	WLCSP49
SAM G55J19	QFN64
	LQFP64

4.1 49-ball WLCSP Pinout

Table 4-2. SAM G55G19 49-ball WLCSP Pinout

A1	PA9	B6	NRST	D4	PB10	F2	PA19/AD2
A2	GND	B7	PB12	D5	PA1	F3	PA17/AD0
A3	PA24	C1	VDDCORE	D6	PA5	F4	PA21
A4	PB8/XOUT	C2	PA11	D7	VDDCORE	F5	PA23
A5	PB9/XIN	C3	PA12	E1	PB2/AD6	F6	PA16
A6	PB4	C4	PB6	E2	PB0/AD4	F7	PA8/XOUT32
A7	VDDIO	C5	PA4	E3	PA18/AD1	G1	VDDIO
B1	PB11	C6	PA3	E4	PA14	G2	VDDOUT
B2	PB5	C7	PA0	E5	PA10	G3	GND
B3	PB7	D1	PA13	E6	TST	G4	VDDIO
B4	PA2	D2	PB3/AD7	E7	PA7/XIN32	G5	PA22
B5	JTAGSEL	D3	PB1/AD5	F1	PA20/AD3	G6	PA15
						G7	PA6

4.2 64-lead QFN/LQFP Pinout

4.2.1 64-lead QFN / LQFP Pinout

Table 4-3. SAM G55J19 64-pin LQFP and QFN Pinout

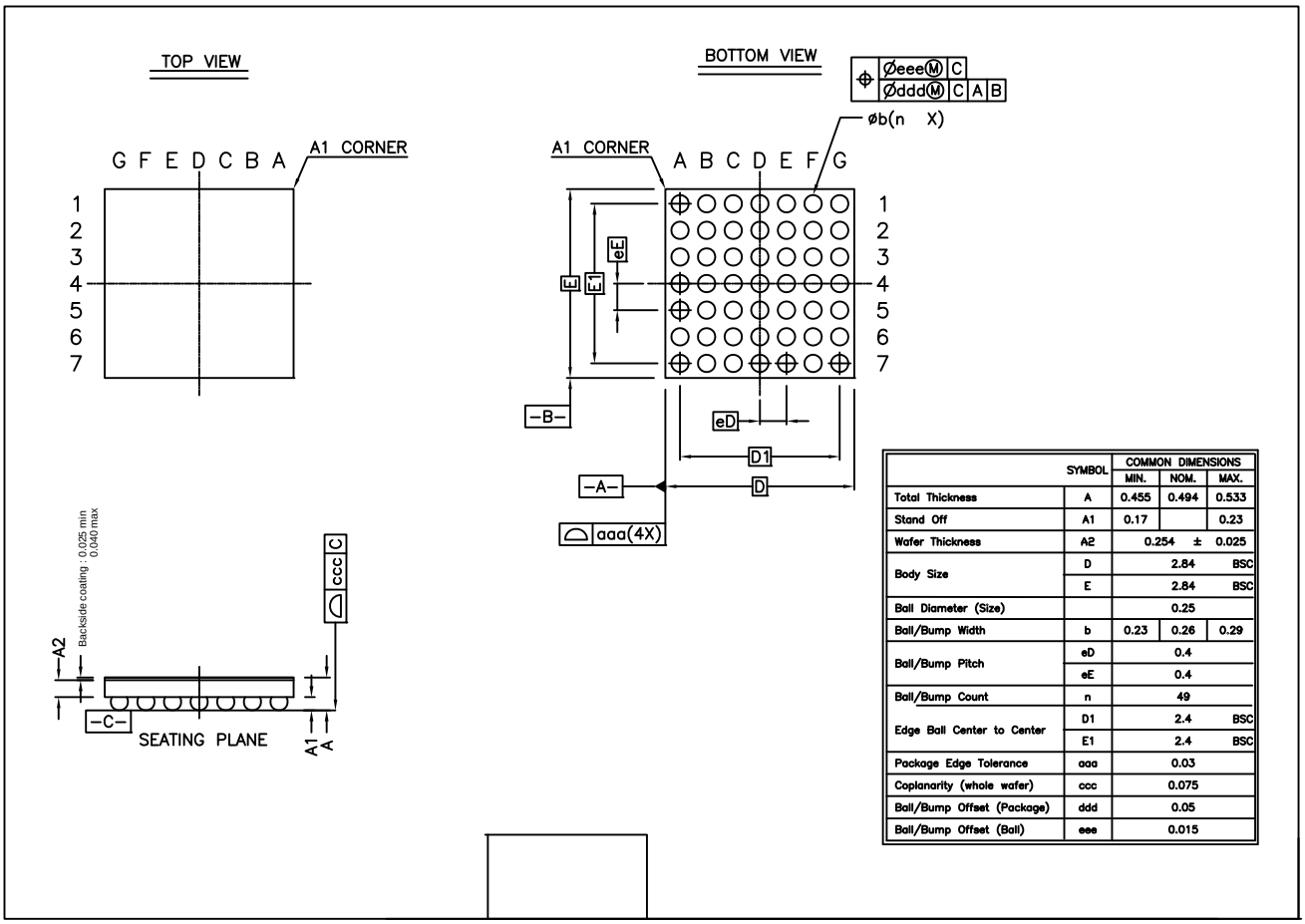
1	VDDIO	17	PA6	33	PA17	49	PA9
2	NRST	18	PA16	34	PA18	50	PB5
3	PB12	19	PA30	35	PA19	51	PA27
4	PA4	20	PA29	36	PA20	52	PA26
5	PA3	21	PA28	37	PB0	53	GND
6	PA0	22	PA15	38	PB1	54	PB6
7	PA1	23	PA23	39	PB2	55	PB7
8	PA5	24	PA22	40	PB3	56	PA25
9	VDDCORE	25	PA21	41	PA14	57	PB13
10	TEST	26	VDDUSB	42	PA13	58	PA24
11	PA7	27	VDDIO	43	PA12	59	PB8/XOUT
12	PA8	28	ADVREF	44	PA11	60	PB9/XIN
13	GND	29	GND	45	VDDCORE	61	PA2
14	PB15	30	VDDOUT	46	PB10	62	PB4
15	PB14	31	VDDIO	47	PB11	63	JTAGSEL
16	PA31	32	VDDIO	48	PA10	64	VDDIO

Note: 1. The bottom pad of the QFN package must be tied to ground.

5. Mechanical Characteristics

5.1 49-lead WLCSP Package

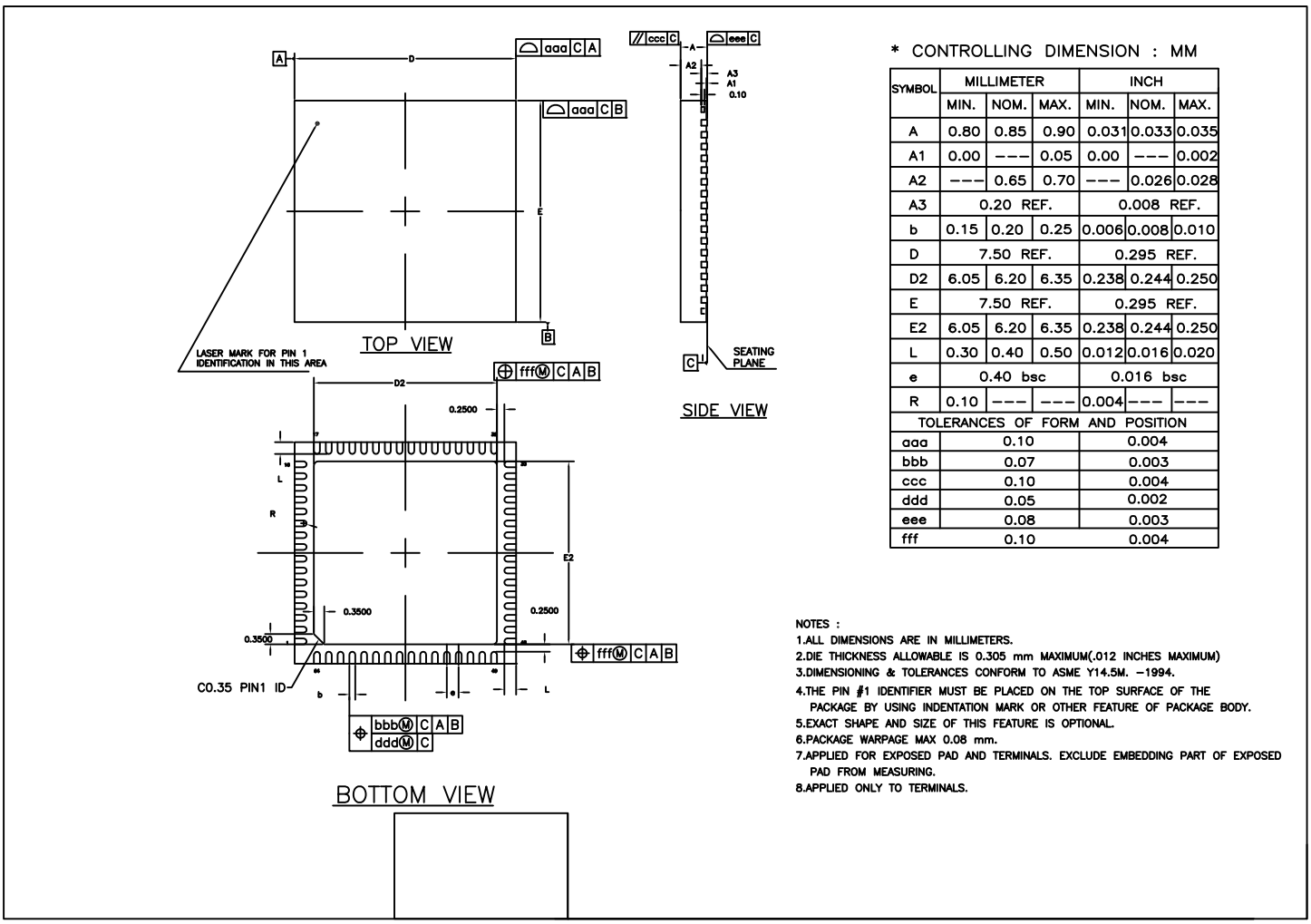
Figure 5-1. 49-lead WLCSP Package Mechanical Drawing



	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOM.	MAX.
Total Thickness	A	0.455	0.494	0.533
Stand Off	A1	0.17		0.23
Wafer Thickness	A2	0.254 ± 0.025		
Body Size	D	2.84 BSC		
	E	2.84 BSC		
Ball Diameter (Size)		0.25		
Ball/Bump Width	b	0.23	0.26	0.29
Ball/Bump Pitch	eD	0.4		
	eE	0.4		
Ball/Bump Count	n	49		
Edge Ball Center to Center	D1	2.4 BSC		
	E1	2.4 BSC		
Package Edge Tolerance	aaa	0.03		
Coplanarity (whole wafer)	ccc	0.075		
Ball/Bump Offset (Package)	ddd	0.05		
Ball/Bump Offset (Ball)	eee	0.015		

5.2 64-lead QFN Package

Figure 5-2. 64-lead QFN Package Mechanical Drawing



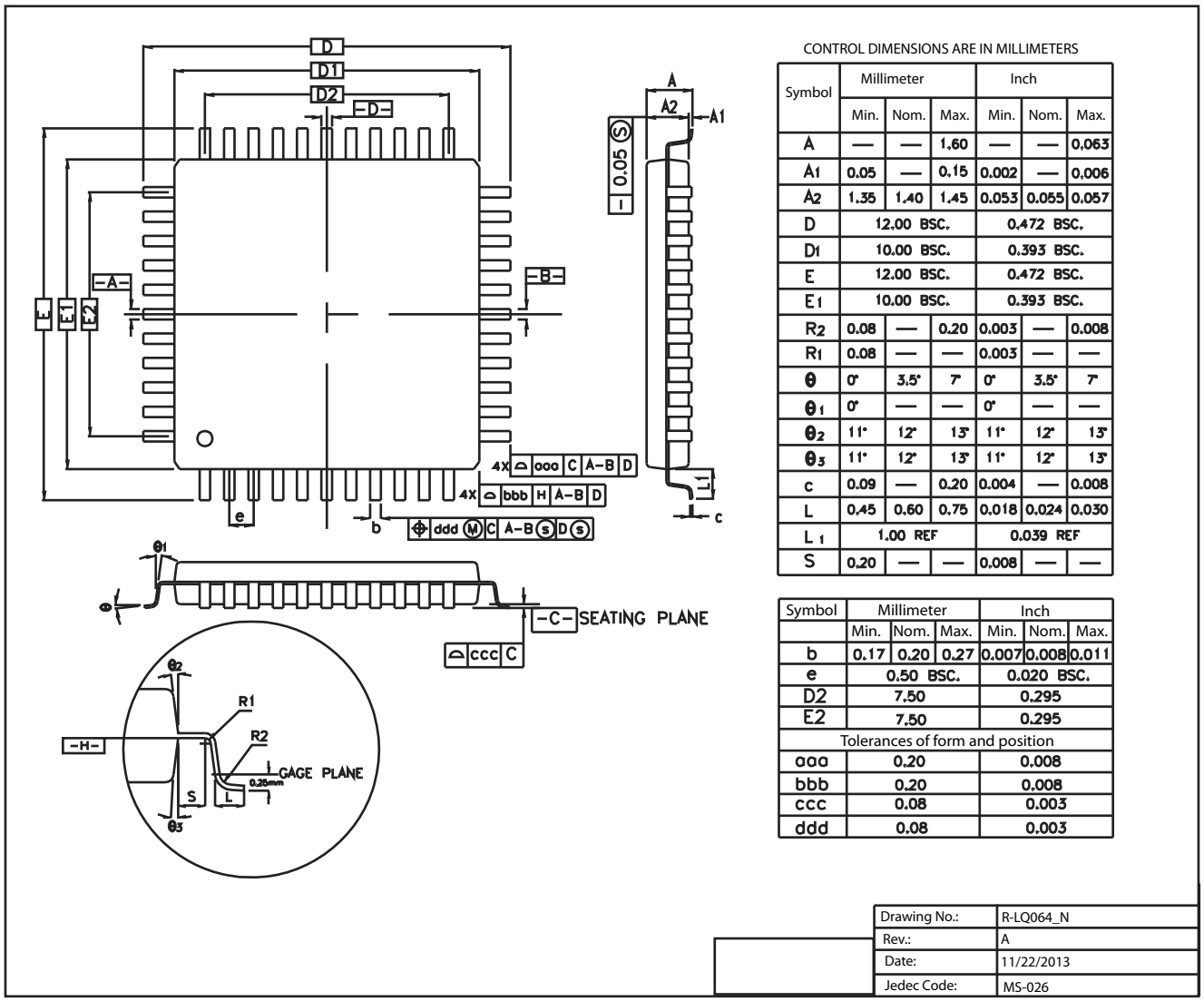
* CONTROLLING DIMENSION : MM

SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.80	0.85	0.90	0.031	0.033	0.035
A1	0.00	---	0.05	0.00	---	0.002
A2	---	0.65	0.70	---	0.026	0.028
A3	0.20 REF.			0.008 REF.		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	7.50 REF.			0.295 REF.		
D2	6.05	6.20	6.35	0.238	0.244	0.250
E	7.50 REF.			0.295 REF.		
E2	6.05	6.20	6.35	0.238	0.244	0.250
L	0.30	0.40	0.50	0.012	0.016	0.020
e	0.40 bsc			0.016 bsc		
R	0.10	---	---	0.004	---	---
TOLERANCES OF FORM AND POSITION						
aaa	0.10			0.004		
bbb	0.07			0.003		
ccc	0.10			0.004		
ddd	0.05			0.002		
eee	0.08			0.003		
fff	0.10			0.004		

NOTES :
1.ALL DIMENSIONS ARE IN MILLIMETERS.
2.DIE THICKNESS ALLOWABLE IS 0.305 mm MAXIMUM(.012 INCHES MAXIMUM)
3.DIMENSIONING & TOLERANCES CONFORM TO ASME Y14.5M. –1994.
4.THE PIN #1 IDENTIFIER MUST BE PLACED ON THE TOP SURFACE OF THE PACKAGE BY USING INDENTATION MARK OR OTHER FEATURE OF PACKAGE BODY.
5.EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
6.PACKAGE WARPAGE MAX 0.08 mm.
7.APPLIED FOR EXPOSED PAD AND TERMINALS. EXCLUDE EMBEDDING PART OF EXPOSED PAD FROM MEASURING.
8.APPLIED ONLY TO TERMINALS.

5.3 64-lead LQFP Package

Figure 5-3. 64-lead LQFP Package Mechanical Drawing



CONTROL DIMENSIONS ARE IN MILLIMETERS

Symbol	Millimeter			Inch		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	1.60	—	—	0.063
A1	0.05	—	0.15	0.002	—	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC.			0.472 BSC.		
D1	10.00 BSC.			0.393 BSC.		
E	12.00 BSC.			0.472 BSC.		
E1	10.00 BSC.			0.393 BSC.		
R2	0.08	—	0.20	0.003	—	0.008
R1	0.08	—	—	0.003	—	—
θ	0°	3.5°	7°	0°	3.5°	7°
θ1	0°	—	—	0°	—	—
θ2	11°	12°	13°	11°	12°	13°
θ3	11°	12°	13°	11°	12°	13°
c	0.09	—	0.20	0.004	—	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	—	—	0.008	—	—

Symbol	Millimeter			Inch		
	Min.	Nom.	Max.	Min.	Nom.	Max.
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.295		
E2	7.50			0.295		
Tolerances of form and position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Drawing No.:	R-LQ064_N
Rev.:	A
Date:	11/22/2013
Jedec Code:	MS-026

6. Ordering Information

Table 6-1. SAM G55 Ordering Information

Ordering Code	MRL	Package	Carrier Type	Operating Temperature Range
ATSAMG55G19A-UUT	A	WLCSP49	Reel	Industrial -40°C to 85°C
ATSAMG55G19B-UUT	B			
ATSAMG55J19A-MU	A	QFN64	Tray	Industrial -40°C to 85°C
ATSAMG55J19B-MU	B			
ATSAMG55J19A-MUT	A		Reel	
ATSAMG55J19B-MUT	B			
ATSAMG55J19A-AU	A	LQFP64	Tray	Industrial -40°C to 85°C
ATSAMG55J19B-AU	B			
ATSAMG55J19A-AUT	A		Reel	
ATSAMG55J19B-AUT	B			

7. Revision History

In the tables that follow, the most recent version of the document appears first.

Table 7-1. SAM G55 Summary Datasheet Rev. 11289ES Revision History

Issue Date	Changes
25-May-16	"Features": "USB 2.0 Device" changed to "Crystal-less USB 2.0 Device" Table 1-1 "Configuration Summary": removed instance of "TWIHS" Figure 2-1 "SAM G55 Block Diagram": repositioned 'VUSB' input and renamed to 'VDDUSB' Table 3-1 "Signal Description List": renamed 'VUSB' to 'VDDUSB'; inserted row "Pulse Density Modulation Interface Controller - PDMICx"; "USB OHCI/FS/IC" changed to "USB OHCI/FS" Table 6-1 "SAM G55 Ordering Information": added MRL B ordering codes

Table 7-2. SAM G55 Summary Datasheet Rev. 11289DS Revision History

Issue Date	Changes
01-Dec-15	Updated "Description" Modified "Features" (Note in "Core" section & "Up to 48 I/O lines" instead of "Up to 32 I/O lines" in "I/O "section) Updated Figure 2-1 "SAM G55 Block Diagram" Table 3-1 "Signal Description List": - modified comments on VDDCORE, DM and DP - PDMCLK0 changed to PDMIC_CLK; PDMDAT0 changed to PDMIC_DAT

Table 7-3. SAM G55 Summary Datasheet Rev. 11289CS Revision History

Issue Date	Changes
16-Jun-15	Removed "Preliminary Status" marking. Modified Section "Description" Updated Figure 2-1 "SAM G55 Block Diagram"(GPBR) Added note to PB0/PB15 in Table 3-1 "Signal Description List" Added note to Section 4.2.1 "64-lead QFN / LQFP Pinout" Replaced ATSAMG55J19-A-AUT with ATSAMG55J19A-AUT in Table 6-1 "SAM G55 Ordering Information"

Table 7-4. SAM G55 Summary Datasheet Rev. 11289BS Revision History

Issue Date	Changes
14-Jan-15	Added "Preliminary Status" marking.

Table 7-5. SAM G55 Summary Datasheet Rev. 11289AS Revision History

Issue Date	Changes
19-Dec-14	First issue.

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